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ABSTRACT OF THE DISCLOSURE

A substrate is plotted into a plurality of blocks, and each block is plotted into one or a plurality of device-forming regions. By using a first manufacturing line, a conductive film, an insulating film and a semiconductor film which constitute TFT are formed in the device-forming region. Then, primary cutting is performed to cut the substrate into the respective blocks and form a plurality of sub-TFT substrates. Then, by using a second manufacturing line, processing is performed for each sub-TFT substrate in accordance with specifications of a liquid crystal panel to be manufactured. Then, secondary cutting is performed to cut the sub-TFT substrate into respective device-forming regions.

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